

END-LOOK PACKAGE INFRARED EMITTING DIODE

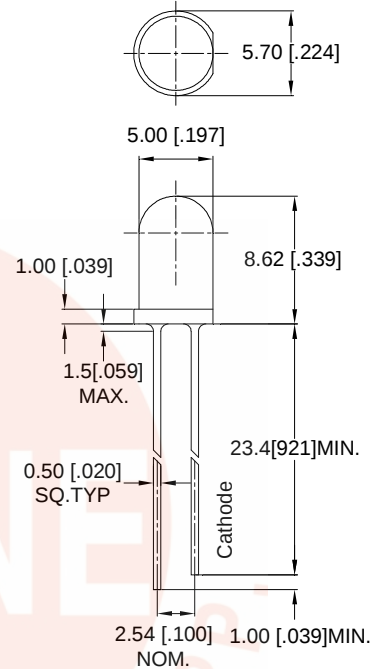
I Features:

1. High radiant power and high radiant intensity.
2. Standard T-1 3/4(5mm)package.
3. Peak wavelength $\lambda_p=850\text{nm}$.
4. Good spectral matching to Si- photo detector.
5. Radiant angle: 30°
6. Lens Appearance: Water Clear.
7. This product doesn't contain restriction Substance, comply RoHS standard

I Applications:

1. Remote Control.
2. Automatic Control System.

I Package Dimensions:



NOTES:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25\text{mm}$ (0.01") unless otherwise specified.
3. Lead spacing is measured where the leads emerge from the package.
4. Specifications are subject to change without notice.

I Absolute Maximum Ratings($T_a=25^\circ\text{C}$)

Parameter	Symbol	Rating	Unit
Power Dissipation	P_d	180	mW
Forward Current	I_F	100	mA
Peak Forward Current ^{*1}	I_{FP}	1.0	A
Reverse Voltage	V_R	5	V
Operating Temperature	T_{opr}	$-40^\circ\text{C} \sim 85^\circ\text{C}$	-
Storage Temperature	T_{stg}	$-45^\circ\text{C} \sim 85^\circ\text{C}$	-

^{*1} (300pps, 10us pulse)

I Optical- Electrical Characteristics (Ta=25°C)

Parameter	Symbol	Test Conditions	Min	TYP	Max	Unit
Radiant Intensity	I _e	I _F =50mA	-	90	-	mW/sr
Forward Voltage	V _F	I _F =50mA	-	1.5	1.8	V
Reverse Current	I _R	V _R =5V	-	-	100	μA
Peak Wavelength	λ _p	I _F =50mA	-	850	-	nm
Spectral Line Half- Width	Δλ	I _F =50mA	-	50	-	nm
Viewing Angle	2θ _{1/2}	I _F =20mA	-	30	-	deg

I Typical Optical-Electrical Characteristic Curves

Fig.1 Spectral Distribution

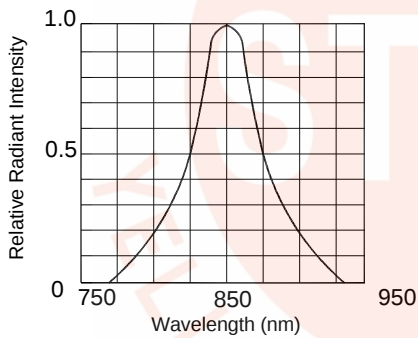


Fig.2 Forward Current Vs Ambient Temperature

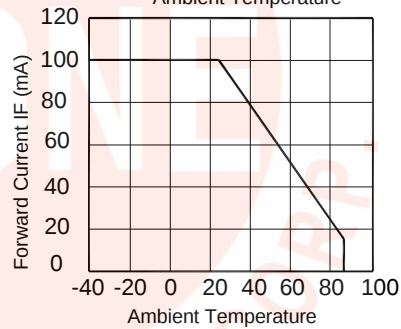


Fig.3 Forward Current Vs Forward Voltage

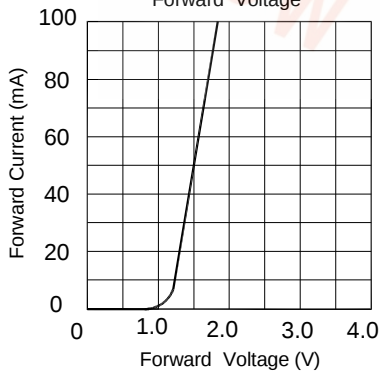


Fig.4 Relative Radiant Intensity Vs Ambient Temperature

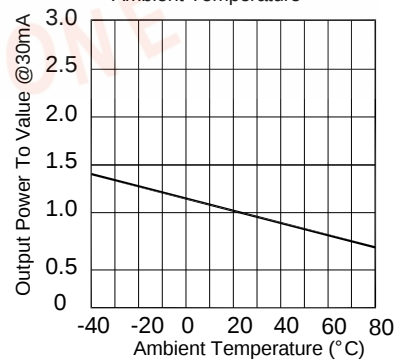


Fig.5 Relative Radiant Intensity Vs Forward Current

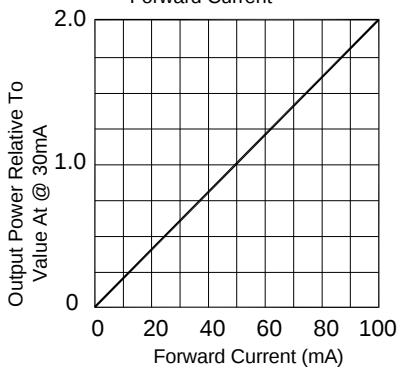
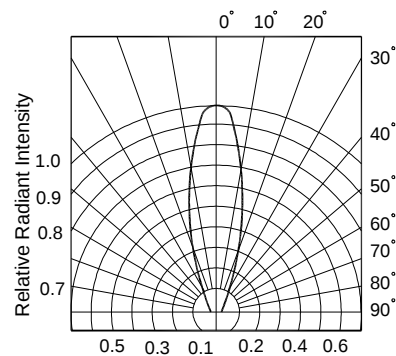
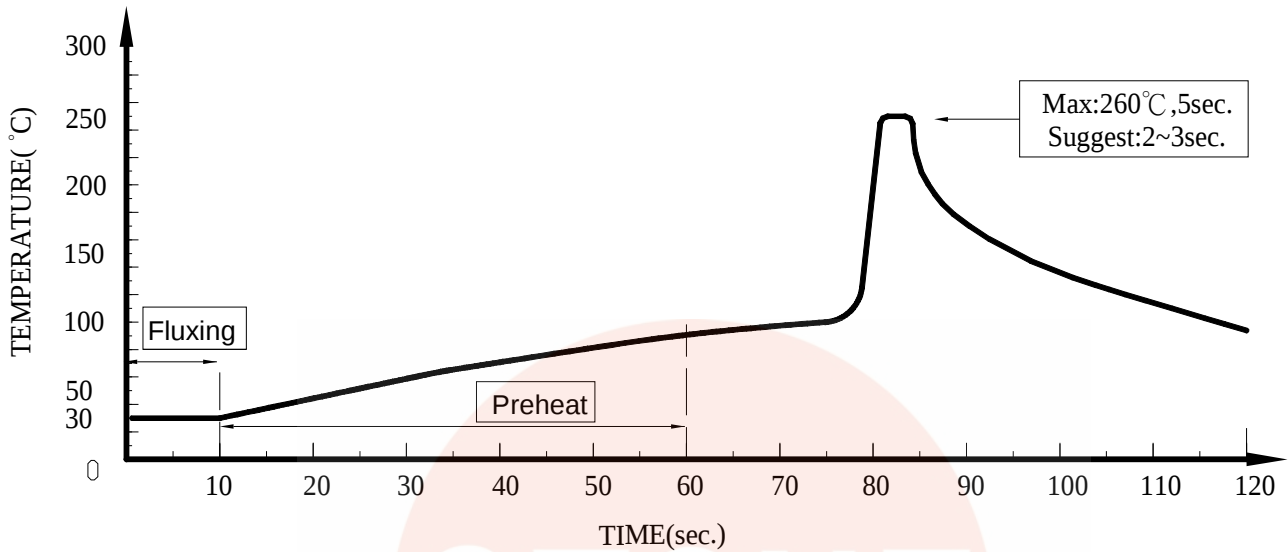


FIG.6 Radiant Diagram



● Dip Soldering

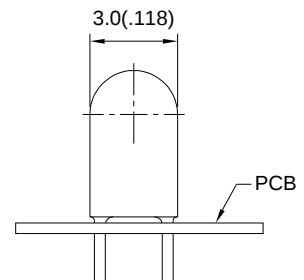


1. Please avoid any external stress applied to the lead-frames and epoxy while the LEDs are at high temperature, especially during soldering
2. DIP soldering and hand soldering should not be done more than one time.
3. After soldering, avoid the epoxy lens from mechanical shock or vibration until the LEDs are back to room temperature.
4. Avoid rapid cooling during temperature ramp-down process
5. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs

● IRON Soldering

A: Max: 350°C Within 3 sec. One time only.

B: The products of 3mm without flange, welding condition of flat plate PCB Max: 350°C Within 2 sec. One time only





Infrared Emitting Diode Specification

I Commodity: Infrared emitting diode

I Intensity Bin Limits (At 50mA)

BIN CODE	Min.(mW/sr)	Max.(mW/sr)
15O	38.08	53.31
16P	53.31	74.63
17Q	74.63	104.48
18R	104.48	146.27
19S	146.27	204.27

NOTES: Tolerance of measurement of Radiant Intensity :±15%